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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	AT	TORNEY DOCKET NO.
Γ		٦	EX	AMINER
			ART UNIT	PAPER NUMBER
			DATE MAILED:	

Please find below and/or attached an Office communication concerning this application or proceeding.

Commissioner of Patents and Trademarks

Office Action Summary

Application No.

Applicant(s)

09/293,188

Yin et al.

Examiner

Phat X. Cao

Art Unit **2814**



	The MAILING DATE of this communication ap	pears on the cover sheet with the correspondence address
Period	for Reply	
A SH	• •	S SET TO EXPIRE 3 MONTH(S) FROM
a	fter SIX (6) MONTHS from the mailing date of this com	f 37 CFR 1.136 (a). In no event, however, may a reply be timely filed immunication. O) days, a reply within the statutory minimum of thirty (30) days will
b	e considered timely.	
	D period for reply is specified above, the maximum stat ommunication.	tutory period will apply and will expire SIX (6) MONTHS from the mailing date of this
- Any		will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). ter the mailing date of this communication, even if timely filed, may reduce any
Status		
1) 🗶	Responsive to communication(s) filed on <u>Jun</u>	1, 2001
2a) 🗶	This action is FINAL . 2b) Th	is action is non-final.
3) 🗀		ance except for formal matters, prosecution as to the merits is Ex parte Quayle, 1935 C.D. 11; 453 O.G. 213.
Dispos	ition of Claims	
4) X	Claim(s) 1, 2, 7-10, and 15-28	is/are pending in the application.
	4a) Of the above, claim(s)	is/are withdrawn from consideration.
5)	Claim(s)	is/are allowed.
6) X	Claim(s) 1, 2, 7-10, and 15-20	is/are rejected.
7) 🗶	Claim(s) <u>21-28</u>	is/are objected to.
8)	Claims	are subject to restriction and/or election requirement.
Applica	ation Papers	
9)	The specification is objected to by the Examin	er.
10)	The drawing(s) filed on	is/are objected to by the Examiner.
11)	The proposed drawing correction filed on	is: a) approved b) disapproved.
12)	The oath or declaration is objected to by the B	Examiner.
Priority	under 35 U.S.C. § 119	
13)	Acknowledgement is made of a claim for fore	ign priority under 35 U.S.C. § 119(a)-(d).
a) _	All b) Some* c) None of:	
	1. Certified copies of the priority document	s have been received.
	2. Certified copies of the priority document	s have been received in Application No
	application from the International	
	ee the attached detailed Office action for a list	
14)	Acknowledgement is made of a claim for dom	estic priority under 35 U.S.C. § 119(e).
Attachm	ent(s)	
15) N	otice of References Cited (PTO-892)	18] Interview Summary (PTO-413) Paper No(s).
	otice of Draftsperson's Patent Drawing Review (PTO-948)	19) Notice of Informal Patent Application (PTO-152)
17) In	formation Disclosure Statement(s) (PTO-1449) Paper No(s).	Other:

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DETAILED ACTION

1. The cancellation of claims 3-6, and 11-14 in Paper No. 10 is acknowledged.

Claim Rejections - 35 USC § 103

- 2. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
 - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 3. Claims 1-2, 7-10, and 15-20 are rejected under 35 U.S.C. 103(a) as being unpatentable over Sekiguchi et al (US. 5.780,908) in view of Hong et al (US. 6,077,774).

Sekiguchi et al disclose in Fig. 3(b) a semiconductor structure comprising: an electrically conductive interconnect disposed within a first dielectric layer 4, the electrically conductive interconnect having an upper surface and including: a titanium/titanium nitride bilayer film 6 disposed within a depression in the first dielectric layer 4; a tungsten film 7 disposed upon the titanium/titanium nitride bilayer film 6 and filling the depression; a passivation layer 7b of tungsten nitride layer, disposed upon the upper surface and having a thickness of less than 50 angstroms (column 16, lines 20-24), the passivation layer 7b formed by exposing the surface of the electrically conductive interconnect 7 to plasma in an atmosphere of ammonia (NH4) for nitriding an area in the vicinity of the surface of the electrically conductive interconnect 7 (column 15, lines

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50-54). Therefore, the passivation layer 7b of tungsten nitride would inherently comprise ammonia (NH4) adsorbed upon the upper surface. It is noted that a first passivation layer comprising tungsten nitride and a second passivation layer comprising ammonia as claimed in claims 7, 15, 17, and 19 do not distinguish from the passivation layer 7b of tungsten nitride comprising ammonia (NH4) of Sekiguchi because the passivation layer 7b is produced by the same processes which are used to produce first and second passivation layers as claimed (i.e., exposing the surface of conductive interconnect in an atmosphere of ammonia).

Sekiguchi et al do not disclose an ILD disposed upon the first dielectric layer 4 and being continuously adhered to the upper surface.

However, Hong et al teach in Fig. 1F the obviousness of forming an ILD 36 upon the dielectric layer 12 and continuously adhered to the upper surface of the electrically conductive interconnect 30. Accordingly, it would have been obvious to form an ILD upon the dielectric layer 4 and continuously adhered to the upper surface of the electrically conductive interconnect 7 of Sekiguchi, because the ILD would provide the known purpose of isolating and protecting the electrically conductive interconnect from the outside ambient.

4. Claims 1-2, 7-10, and 15-20 are rejected under 35 U.S.C. 103(a) as being unpatentable over Sekiguchi et al (US. 5,780,908) in view of Liao (US. 6,114,238).

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As discussed above, Fig. 3(b) of Sekiguchi et al substantially reads on the above claims, except it does not disclose an ILD disposed upon the first dielectric layer and being continuously adhered to the upper surface of the conductive interconnect.

However, in view of Fig. 1 of Liao, it would have been obvious to form an ILD upon the dielectric layer 4 and continuously adhered to the upper surface of the conductive interconnect 7 of Sekiguchi, because the ILD would provide the known purpose of isolating and protecting the electrically conductive interconnect from the outside ambient.

Allowable Subject Matter

5. Claims 21-28 are objected to as being dependent upon a rejected base claim, but would be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims.

The prior art of record fails to disclose all the limitations recited in the above claims, including the limitation of having ammonia derivative comprising nitrogen-containing silane.

Response to Arguments

6. Applicant's arguments with respect to the claimed invention have been considered but are moot in view of the new ground(s) of rejection.

Applicant asserted that claims 1-2, 7-10, and 15-16 should be in condition for allowance because independent claims 7-8 and 15-16 are indicated allowable by the Examiner in the last

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Office action, and because independent claims 1 and 9 has been rewritten to incorporate the limitations of dependent claims which the Examiner has indicated contains allowable subject matter.

However, the indication of allowability of independent claims 7-8, 15-16, 1, and 9 are withdrawn because the scopes of the above claims are changed by replacing "ammonia and its derivatives" with "ammonia or derivatives thereof" in amendment filed 6/1/01. Therefore, the new ground of rejection is applied.

Conclusion

7. Applicant's amendment necessitated the new ground(s) of rejection presented in this Office action. Accordingly, **THIS ACTION IS MADE FINAL**. See MPEP § 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the date of this final action.

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8. Any inquiry concerning this communication or earlier communications from the examiner

should be directed to Phat X. Cao whose telephone number is (703) 308-4917. The Examiner

can normally be reached on Monday through Thursday. If attempts to reach the Examiner by

telephone are unsuccessfully, the Examiner's supervisor, Olik Chaudhuri, can be reached on

(703) 306-2794.

Any inquiry of a general nature or relating to the status of this application should be

directed to the Group receptionist whose telephone number is (703) 308-0956. Group 2800 fax

number is (703) 308-7722 or (703) 308-7724.

PC

July 31, 2001

Cao, Phat X.

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Patent Examiner

Technology Center 2800